FILE OROLIA ART_CARD

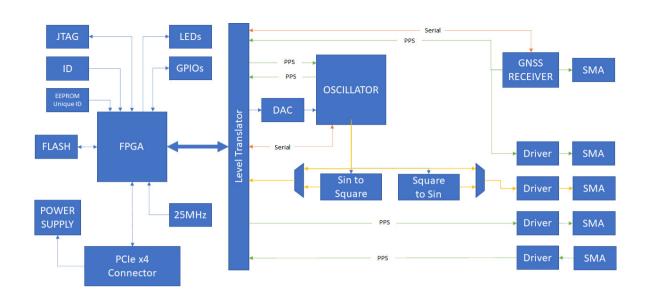
Réf PCB:	ART	CARD-	Rev 3
	~!\!		1101

7 SHEETS OF ELECTRICAL SCHEMATION	
	'C

- □ ASSEMBLY DRAWING TOP
- □ ASSEMBLY DRAWING BOTTOM
- ⇒ 1 SILKSCREEN TOP
- ⇒ 1 SOLDER MASK TOP
- □ COPPER LAYER TOP
- □ COPPER LAYER INNER 1
- ⇒ 1 COPPER LAYER INNER 2
- ⇒ 1 COPPER LAYER INNER 3
- ⇒ 1 COPPER LAYER INNER 4
- ⇒ 1 COPPER LAYER BOTTOM
- ⇒ 1 SOLDER MASK BOTOM
- ⇒ 1 SILKSCREEN BOTTOM
- □ DRILL DRAWING
- ⇒ 1 STACK-UP



1 bis Avenue du Bois l'Abbé

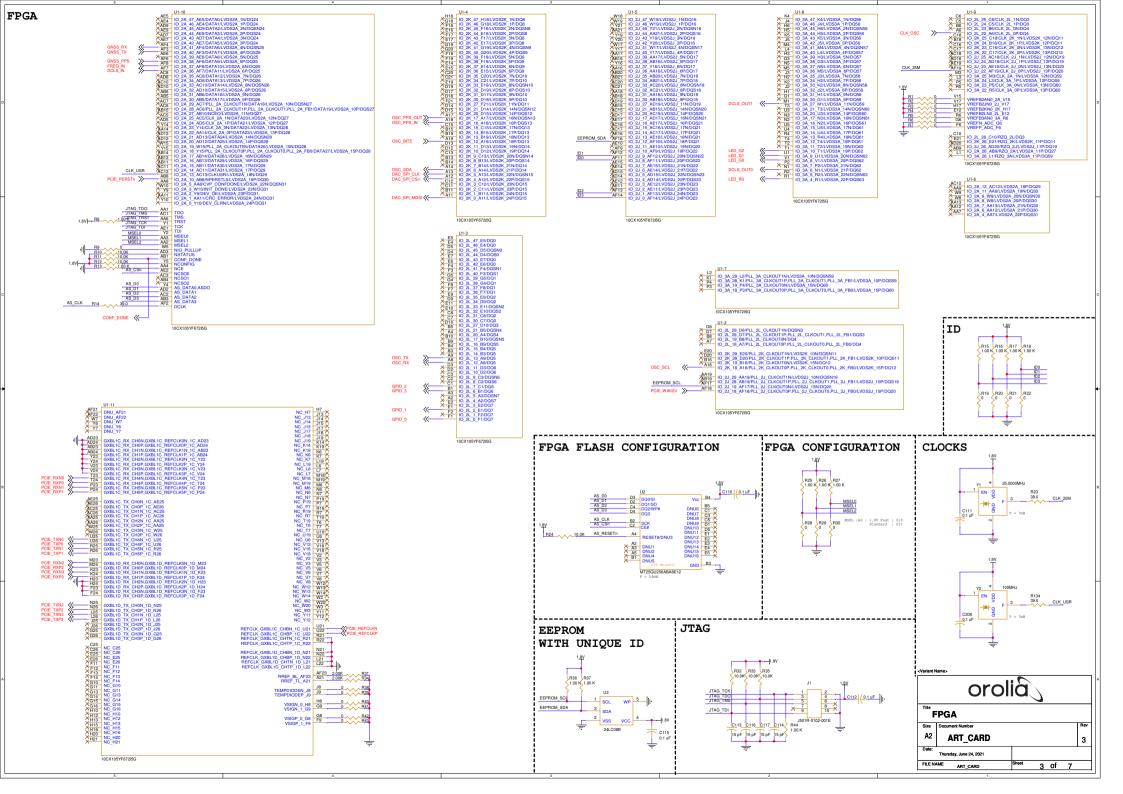


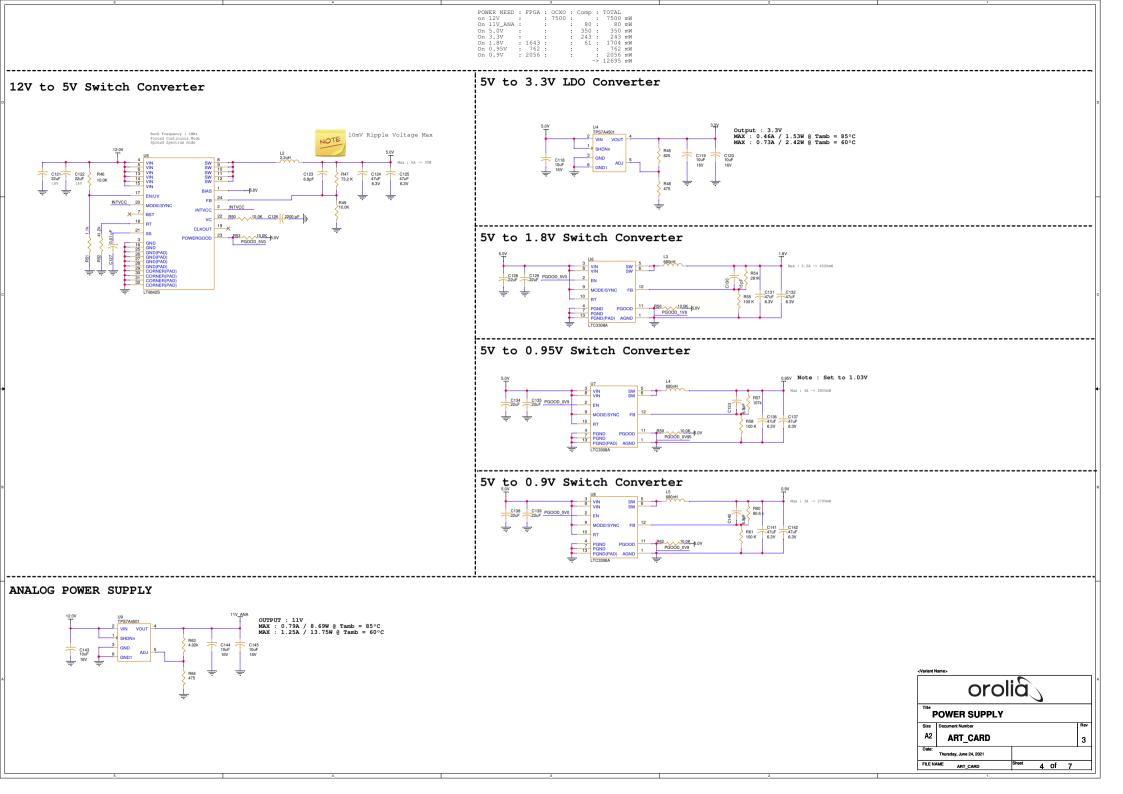


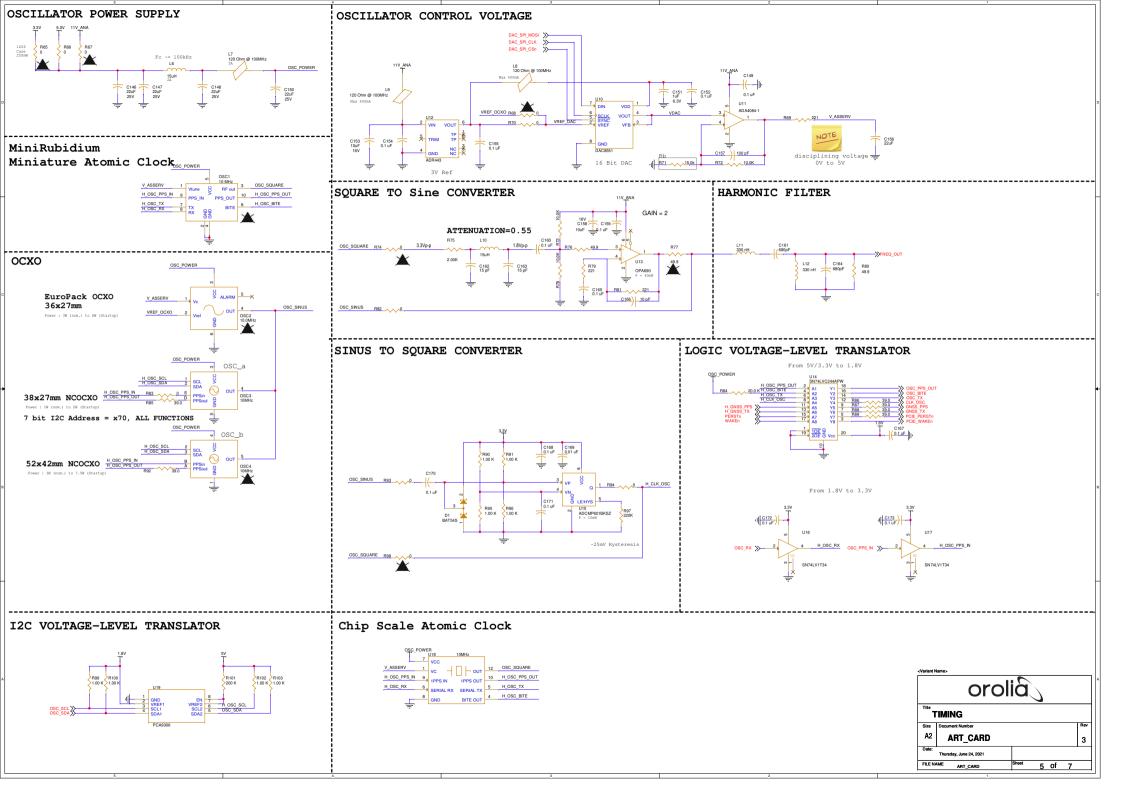


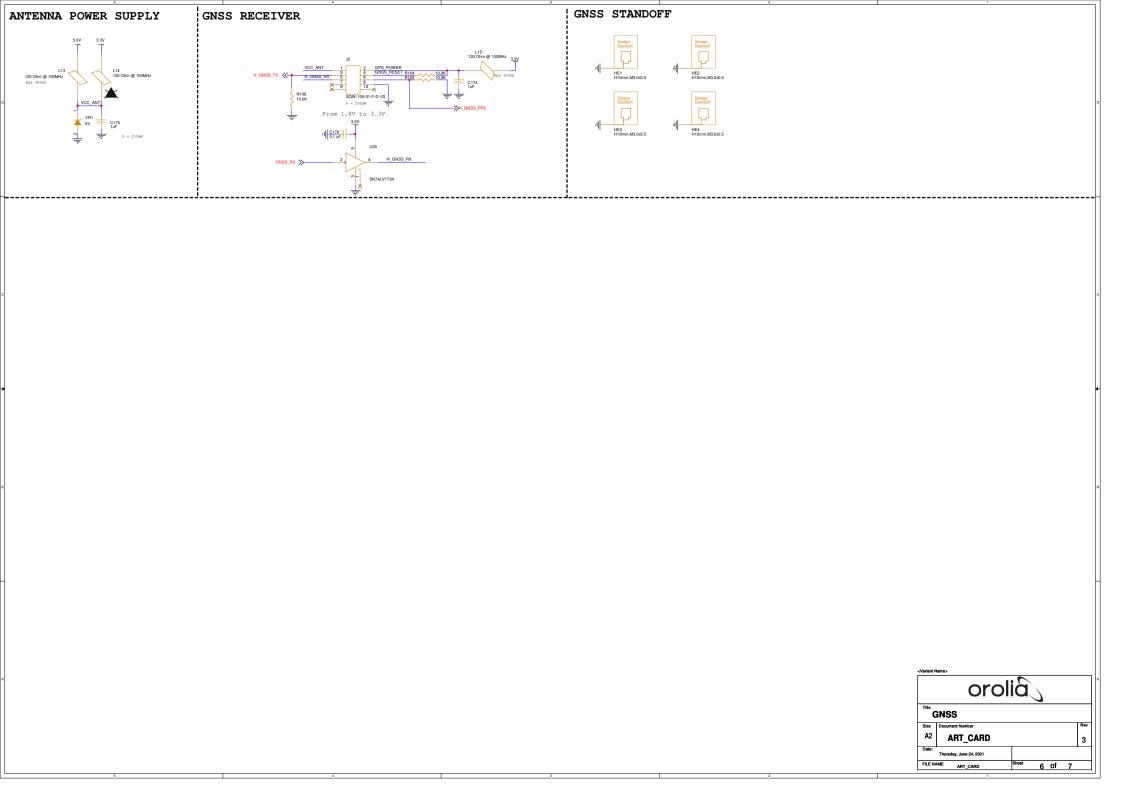
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Title (VERVIEW				
Size	Document Number				Rev
A2	ART_CARD				3
Date:	Thursday, June 24, 2021				
FILE N	AME ART CARD	Sheet		of	

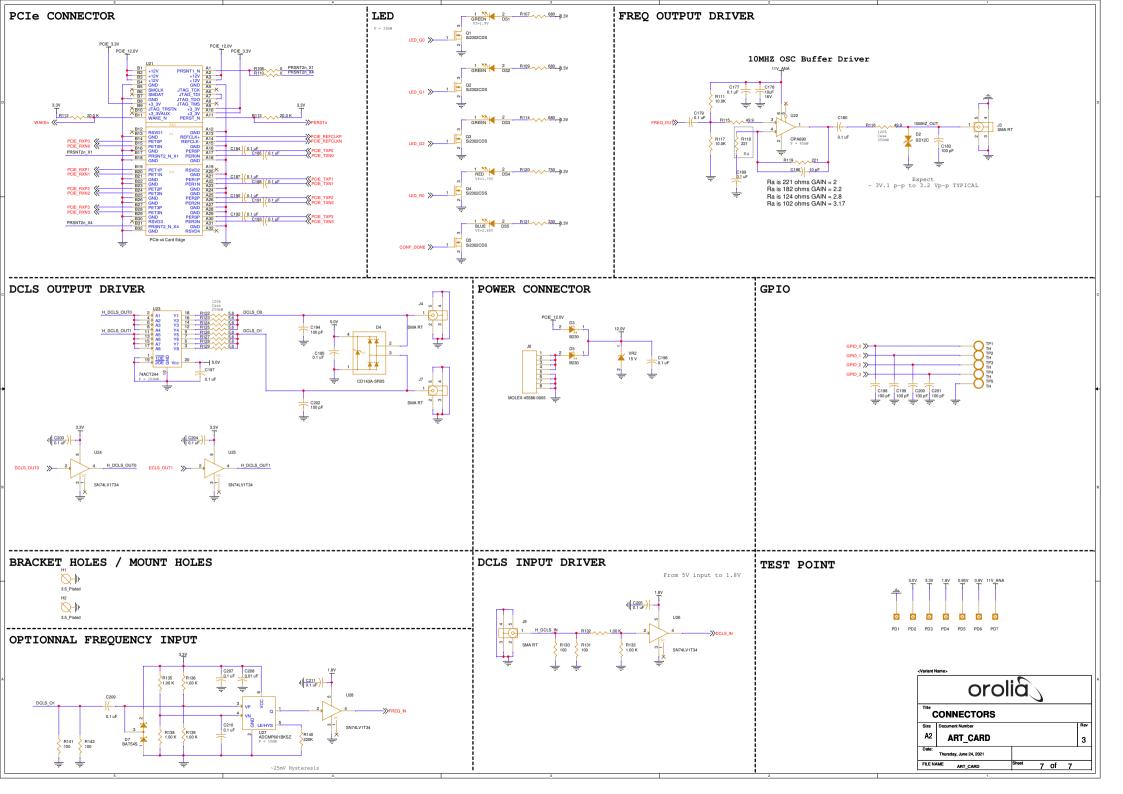


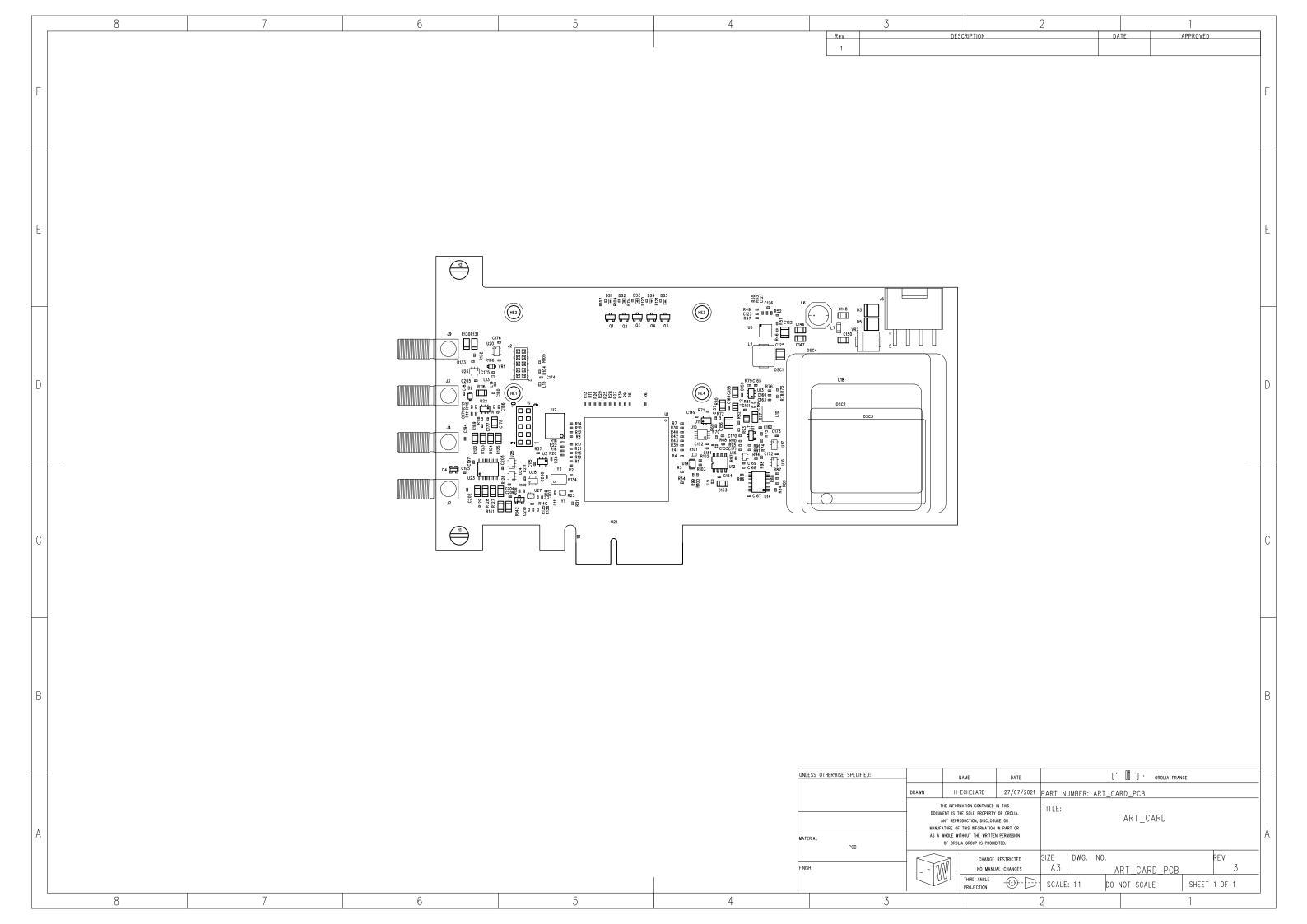


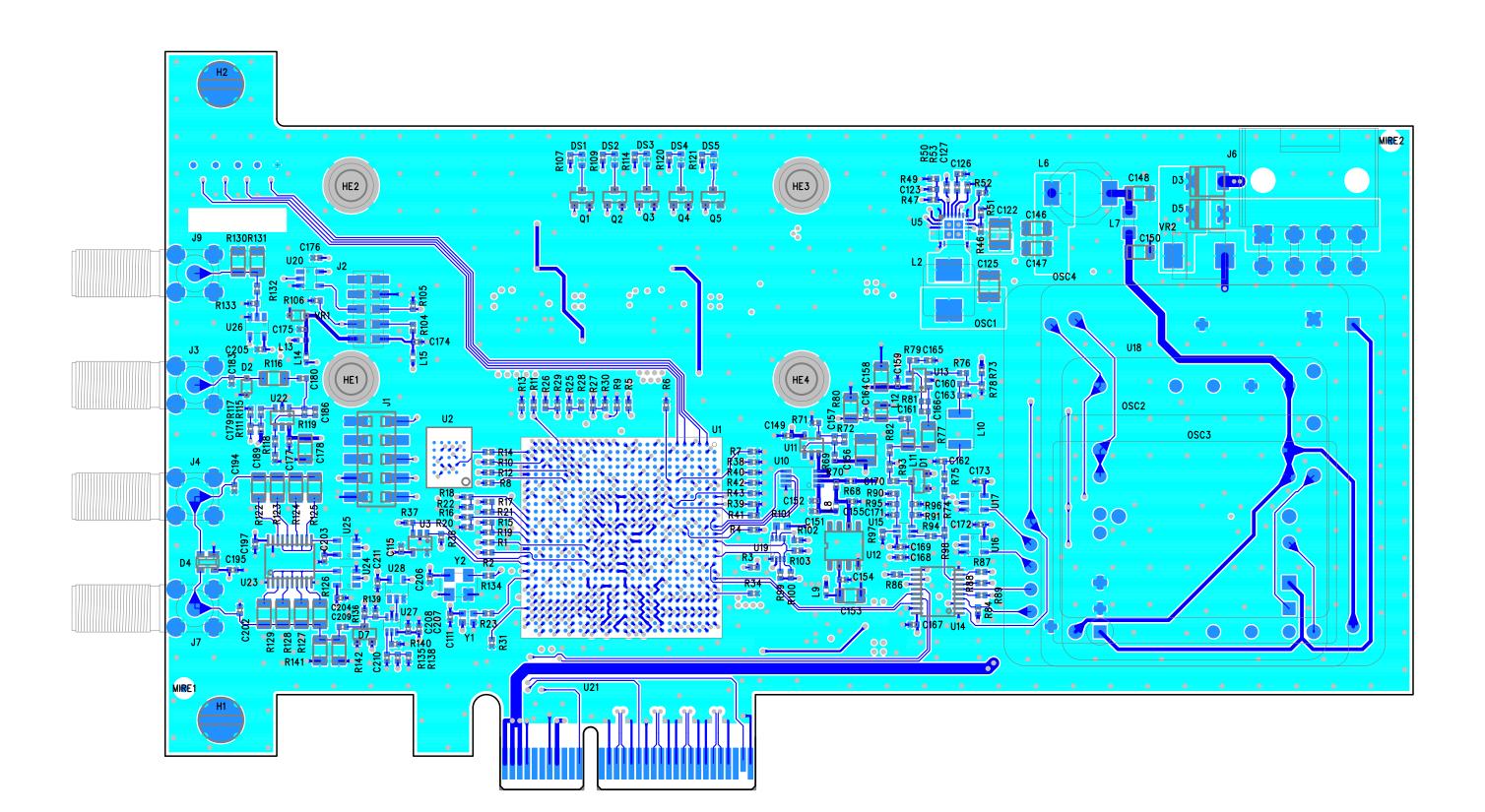


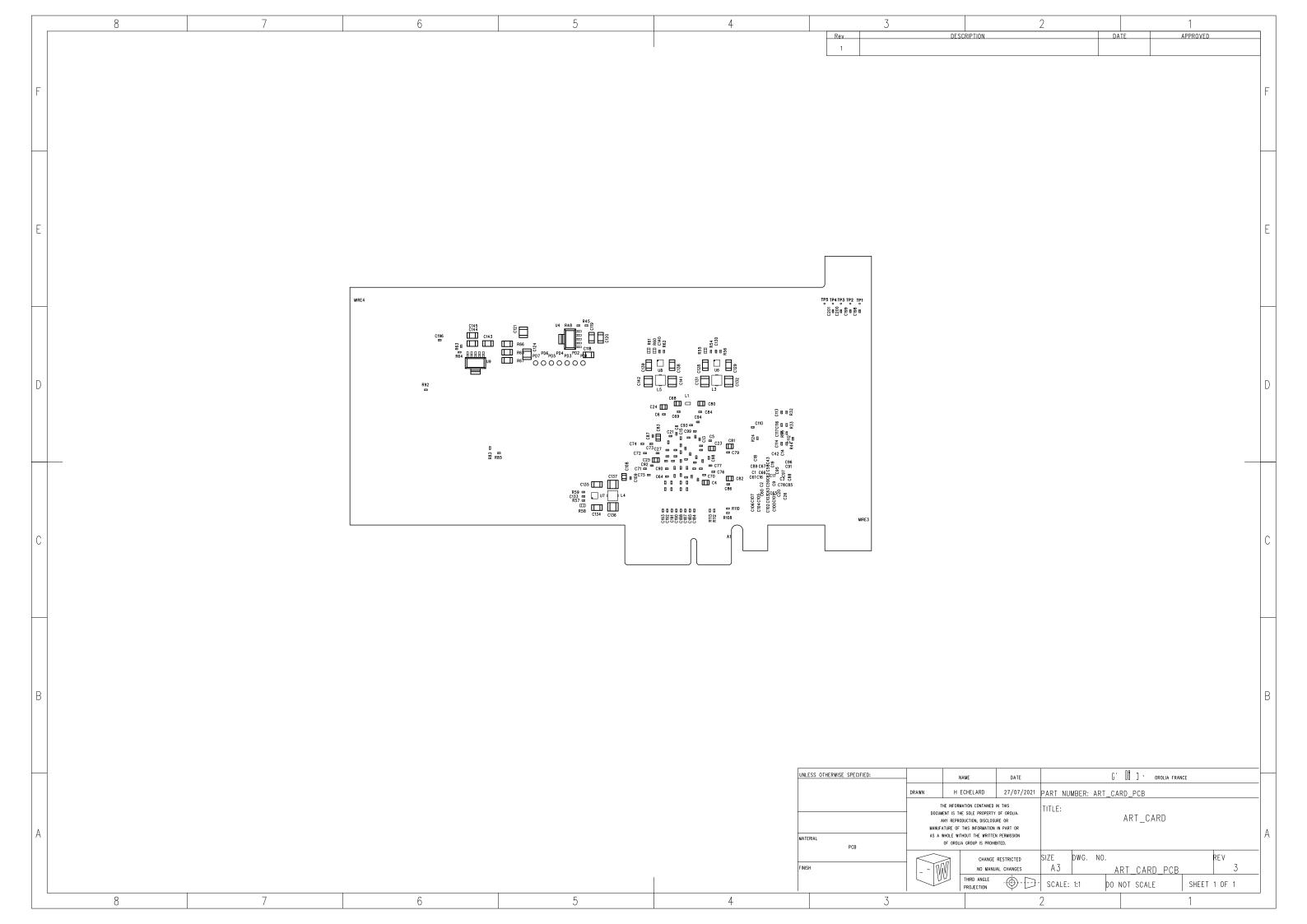


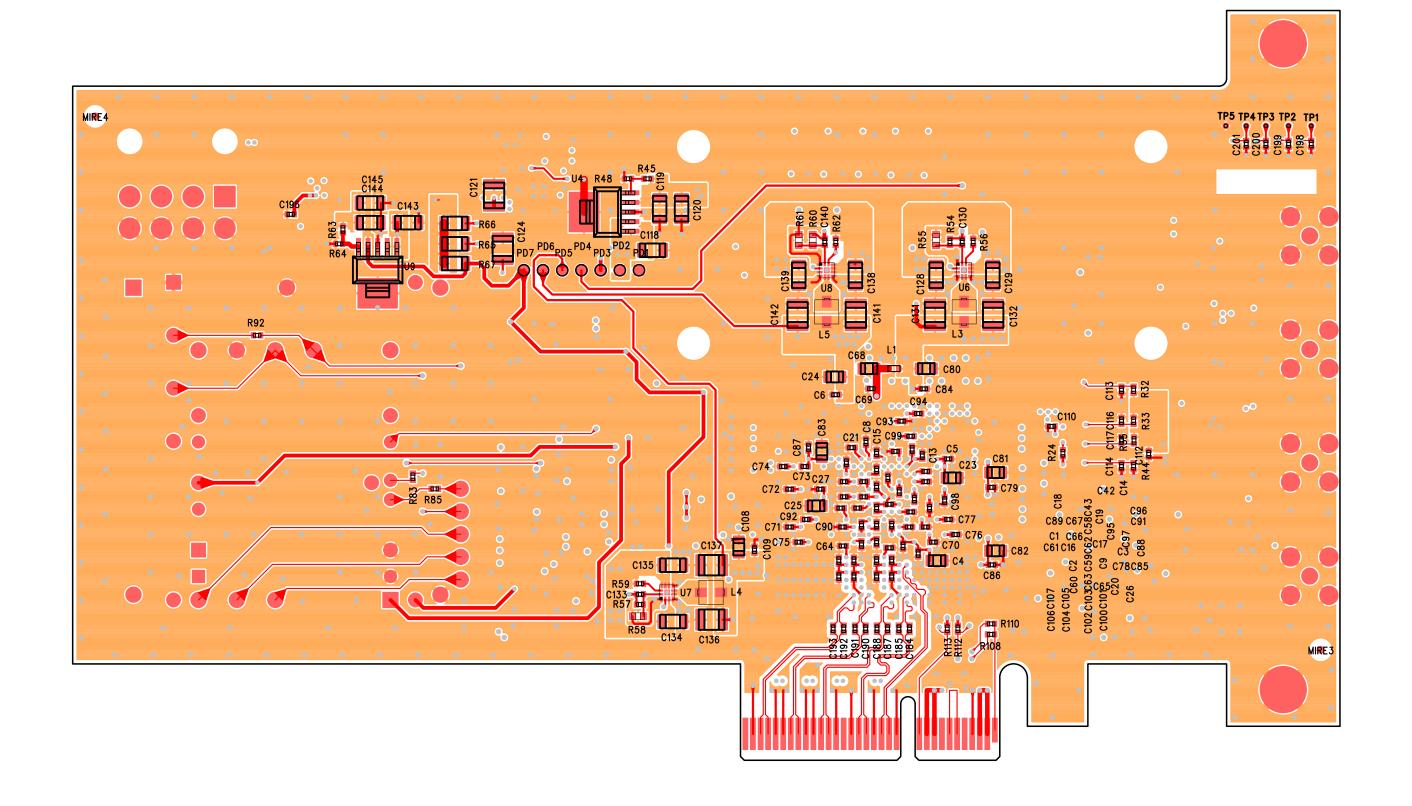


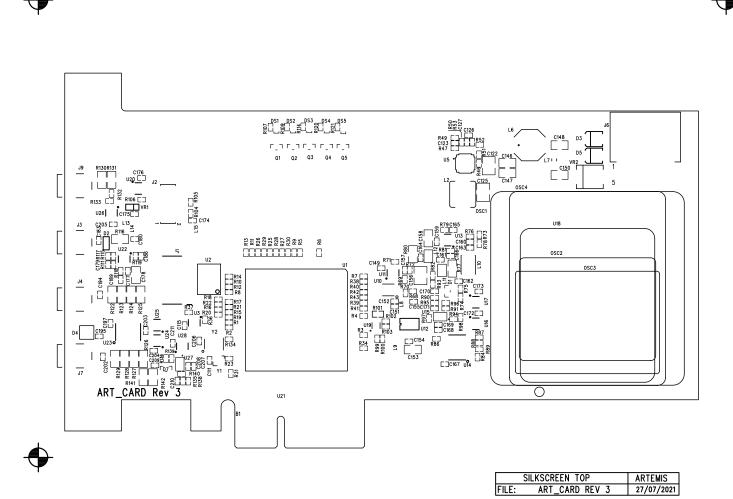


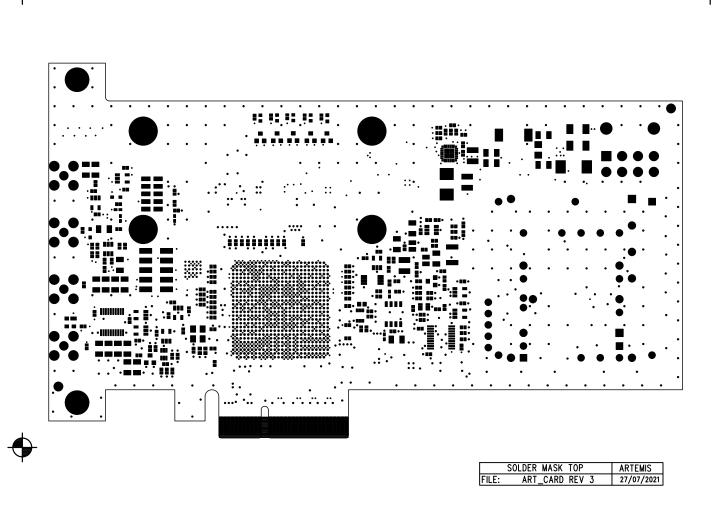






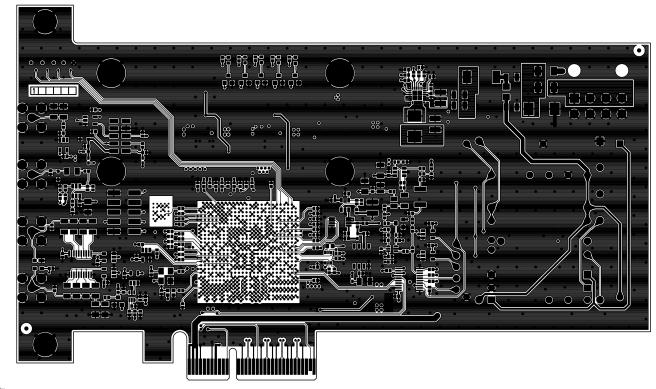






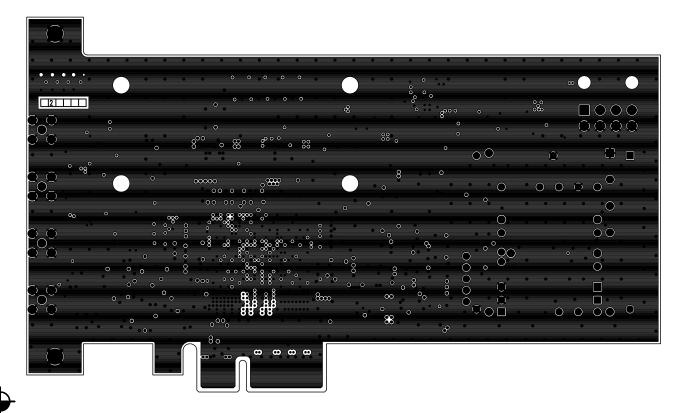






	TOP LAYER		ARTEMIS
FILE:	ART CARD	REV 3	27/07/2021

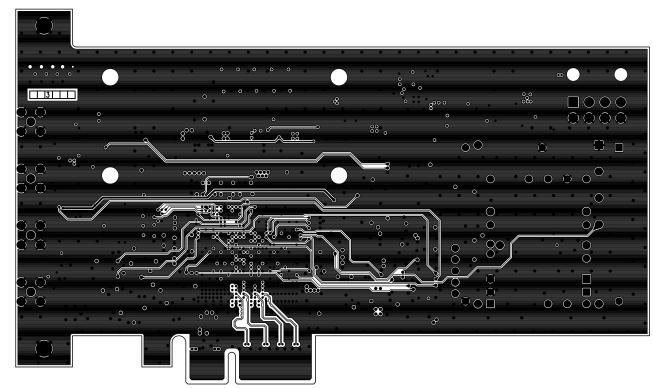




INTERNAL 1 LAYER ARTEMIS
FILE: ART_CARD REV 3 27/07/2021



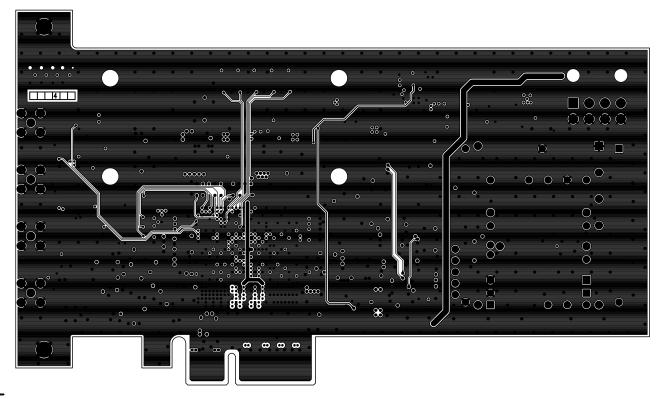




	INTERNAL 2 LAYER	ARTEMIS
FILE:	ART_CARD REV 2	27/07/2021





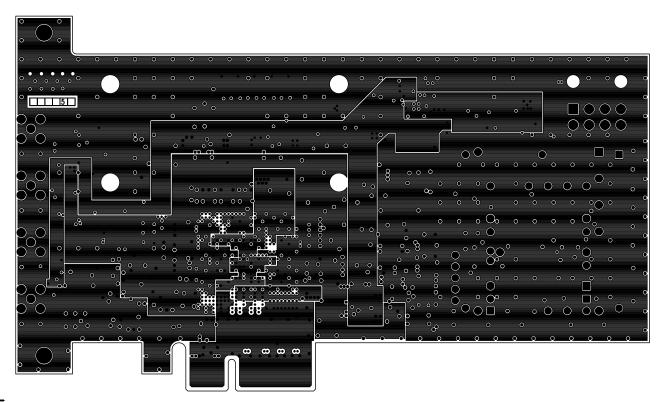


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	INTERNAL 3 LAYER	ARTEMIS
FILE:	ART_CARD REV 3	22/07/2021





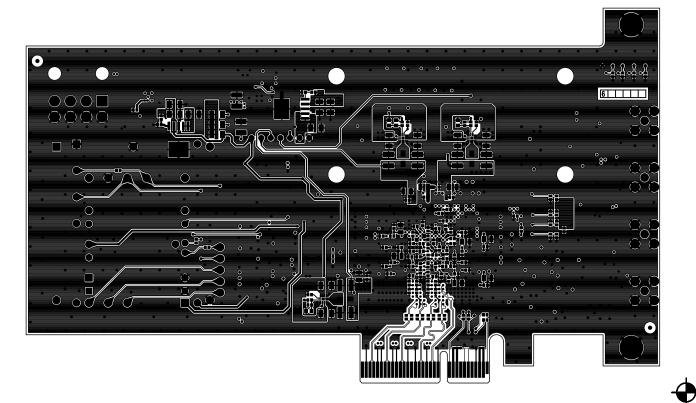


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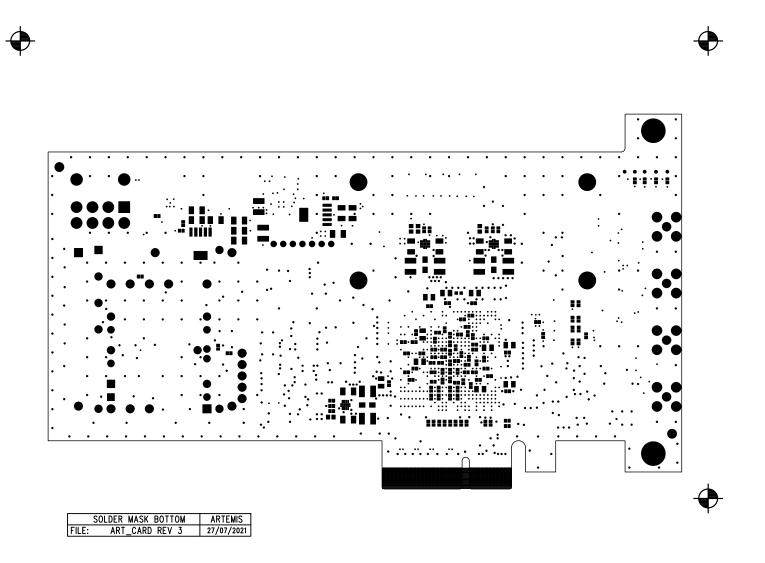
FILM: COUCHE INTERNE 4 ARTEMIS
FILE: ART_CARD REV 3 27/07/2021

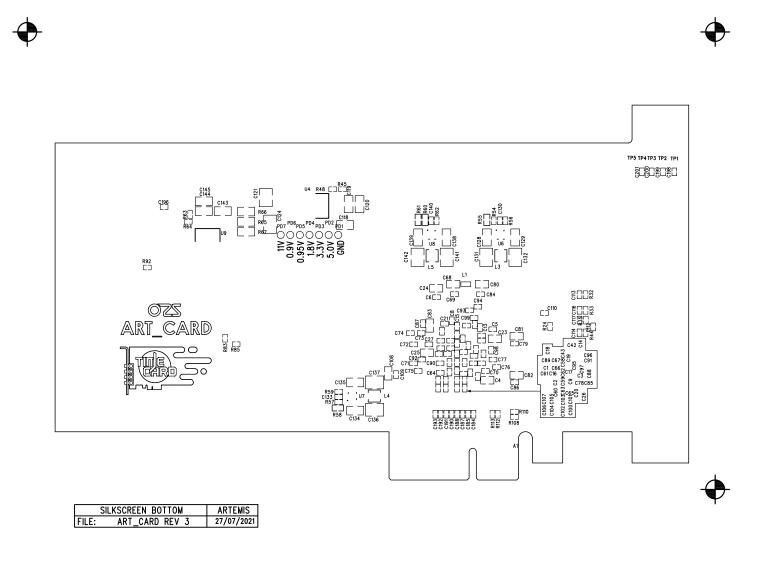


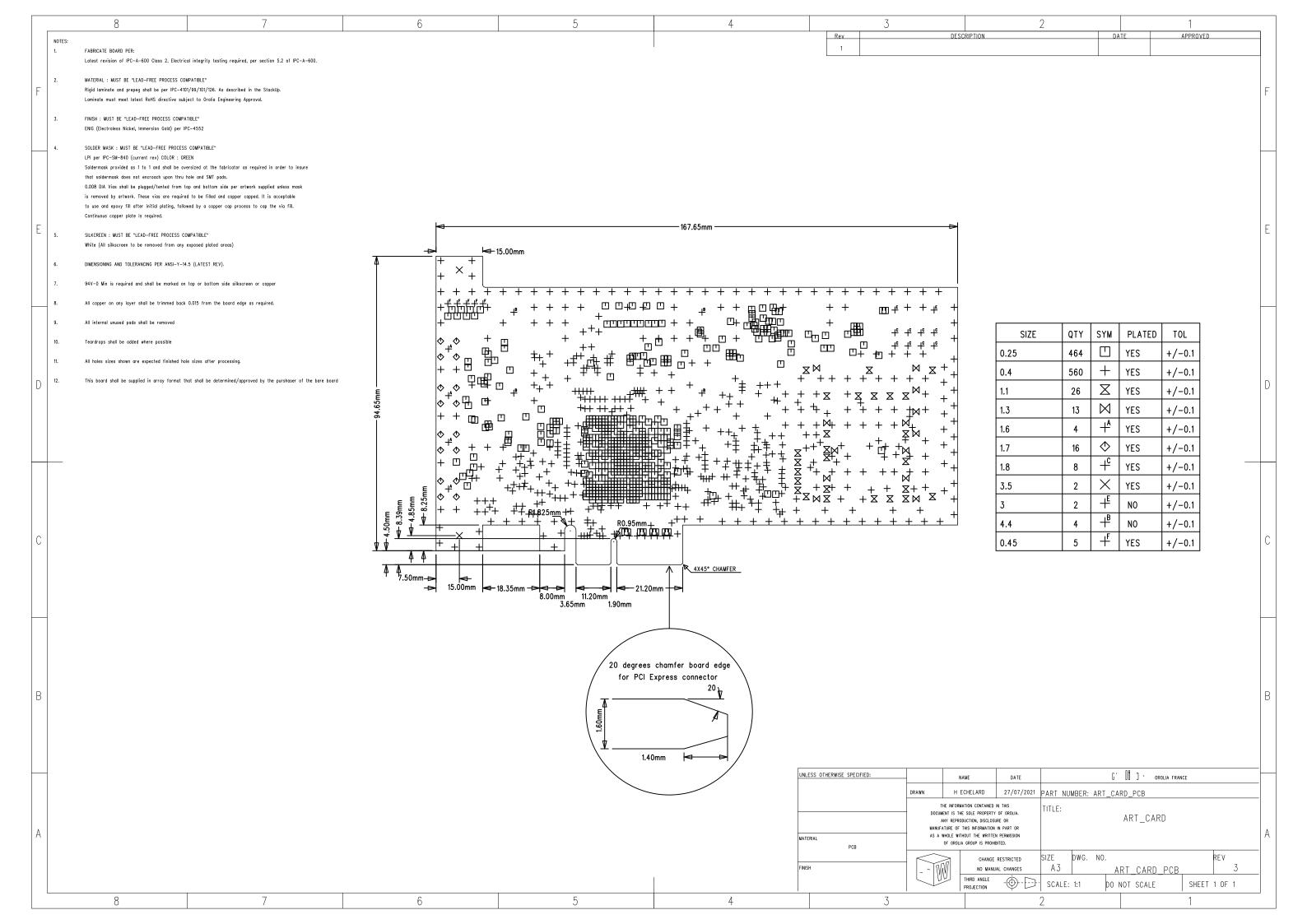




BOTTOM LAYER ARTEMIS
FILE: ART_CARD REV 3 27/07/2021









Layer	Stack up	Supplier	Description	Supplier Description	Туре	Base Thickness	Finish Thickness	Mask Thickness	εr	Loss Tangent	Resin Content	Impedance ID
			Solder resist	LPI	Solder resist			0.020	4.100	0.0000		
1			Foil	17um Copper Foil	Foil	0.018	0.040					1, 2
		VENTEC	VT47-2113	VT-47	PREPREG	0.106	0.095		4.060	0.0000	57.000	
2						0.017	0.017					
3		VENTEC	VT-47	0.127mm	Core	0.127 0.017	0.127 0.017		4.350	0.0000	0.000	3, 4
		VENTEC	VT47-2116	VT-47	PREPREG	0.132	0.121		4.150	0.0000	54.000	0, 4
(VENTEC		0.711mm	Core	0.711	0.711			0.0000	0.000	
Ġ			VT47-2116	VT-47	PREPREG	0.132	0.121			0.0000	54.000	
1		VEIVILO	V147-2110	V1-47	THETHEG	0.017	0.017		4.150	0.0000		5, 6
· ,		VENTEC	VT-47	0.127mm	Core	0.127	0.127		4.350	0.0000	0.000	5, 6
5						0.017	0.017					
		VENTEC	VT47-2113	VT-47	PREPREG	0.106	0.095		4.060	0.0000	57.000	
6	+1		Foil	17um Copper Foil	Foil	0.018	0.040					7, 8
			Solder resist	LPI	Solder resist			0.020	4.100	0.0000		

Copper Thickness = 0.148 | Dielectric Thickness = 1.399 | Solder Mask Thickness = 0.040 | Stack Up Thickness = 1.546 | Stack Up Thickness with Soldermask = 1.586

Impedance ID	Structure Image	Structure Name	Impedance Signal Layer	Ref. Plane 2 in Layer	Ref. Plane 1 in Layer	Lower Trace Width (W1)	Trace Separation (S1)	Ground Strip Separation (D1)	Broadside 2nd Layer	Calculated Impedance	Target Impedance	Tol (+/- %)	Coating Between Traces (C3)
		Coated Microstrip 1B	1	0	2	0.150	0.000	0.000	0	50.090	50.000	10.000	0.000
2		Edge Coupled Coated Microstrip 1B	1	0	2	0.150	0.150	0.000	0	87.470	85.000	10.000	0.020
3		Offset Stripline 1B1A	3	5	2	0.160	0.000	0.000	0	50.950	50.000	10.000	0.000
4		Edge Coupled Offset Stripline 1B1A	3	5	2	0.160	0.150	0.000	0	85.010	85.000	10.000	0.000
5		Offset Stripline 1B1A	4	5	2	0.160	0.000	0.000	0	50.950	50.000	10.000	0.000
6		Edge Coupled Offset Stripline 1B1A	4	5	2	0.160	0.150	0.000	0	85.010	85.000	10.000	0.000
7		Coated Microstrip 1B	6	0	5	0.150	0.000	0.000	0	50.090	50.000	10.000	0.000

StackName: Ouestronic_PCl Express_246183-Q_6L_VT47	Version:	Revision:	Modification:	Date of Revision:	Editor	
Date: 28/01/2021	Associated Documents:					
Author: Mostefa Abdali						Page 1/2
Department: IDS						
Site: Tewkesbury						



Impedance ID	Structure Image	Structure Name	Impedance Signal Layer	Plane 2	Ref. Plane 1 in Layer	Lower Trace Width (W1)		Ground Strip Separation (D1)	Broadside 2nd Layer	Calculated Impedance	Target Impedance	Tol (+/- %)	Coating Between Traces (C3)	
8	andanan	Edge Coupled Coated Microstrip 1B	6	0	5	0.150	0.150	0.000	0	87.470	85.000	10.000	0.020	

Column	Drill	1st	2nd	Drill Type	Minimum	Fill	Data	Minimun
Position I	Image	Layer	Layer		Size	Type	Filenames	Pad Size
	- {{	1	6	Mechanical PTH	0.250	None		0.500

<u>Notes</u>

StackName: Ouestronic_PCl Express_246183-Q_6L_VT47	Version:	Revision:	Modification:	Date of Revision:	Editor		
Date: 28/01/2021	Associated Documents:						
Author: Mostefa Abdali						Page 2/2	
Department: IDS							
Site: Tewkesbury							



Angers Technopole
1 bis Avenue du Bois l'Abbé
49070 BEAUCOUZÉ FRANCE

Phone: +33(0)2-41-48-98-68 b.jule@artemis-cad.com

www.artemis-cad.com

TECHNICAL SPECIFICATION

IPC-A-600

CUSTUMER: OROLIA

MANUFACTURER:

PCB Reference :	ART_CARD	Inc	lex: Rev 3
✓ PCB Unit	Unit PCB dimensions :	168 >	C 95 mm
Panel PCB: 0	Panel dimensions :	0 >	C 0 mm
Material: FR4	Surface: 1	,59 dm ² Track / G	ap: 0,15 / 0,15 mm
PCB Type :	MC6 Finish	n Copper Thikness (µm) :	12µ 17,5µ 35µ 40µm
PCB Thickness (mm) :	16/10	External Layer : Intern Layer :	
Technology ✓	Plated Trough Hole	Via type : Hole	e / pads ratio : 0,25/0,55
✓ Traditional	Press-fit Hole	✓ Traditional Via	Via in pad
✓ SMT	Autre	Laser Via	Stacked Staggered
Surface Treatement Finished	i	Blinded Via	Couche départ et d'arrivée
✓ Ni/Au Chemical	Sn/Pb surfondu	Buried Via	Couche départ et d'arrivée
Sn/Cu HAL	Autre	Filled Via	Resin Copper
Peelable Solder Mask	Standard		TOP BOTTOM
Solder Mask ✓	Photo-imageable	Green	✓ TOP ✓ BOTTOM
Silkscreen √	Ink	White	✓ TOP ✓ BOTTOM
Electrical Test			✓ Yes No
✓ Impedance control :		✓ Produced	Measured
50 ohms on layer 1, 3 and 4			
✓ Differential Pairs :		✓ Produced	Measured
85 ohms on layer 1, 3 and 6			
✓ Stack-up :	Ouestronic_PCI Expres	ss_246183-Q_6L_VT47.pd	f
Milling	Milling Diameter :	0 mm	
Comments :			